

**APPARATUS AND METHOD
FOR
PACKAGING IMAGE SENSING SEMICONDUCTOR CHIPS**

ABSTRACT OF THE DISCLOSURE

An method and apparatus for fabricating a die having imaging circuitry and fabricating a lid having a transparent region and support regions having a predetermined height. The lid is fabricated by applying a photo-sensitive adhesive layer with a thickness substantially equal to the predetermined height to a transparent plate and patterning the photo-sensitive adhesive layer to form the transparent region and the support regions. Once fabrication of the lid is complete, it is mounted directly onto the die so that the transparent region generally covers the imaging circuitry. The resulting apparatus includes a lid mounted directly onto the die with the transparent region generally positioned above the imaging circuitry. A gap, having a height dimension substantially equal to the predetermined height of the support regions of the lid, is spaced between the transparent region of the lid and the imaging circuitry on the die.